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	PAT. NO.	Title
1	11,078,337	High-.chi. block copolymers for directed self-assembly
2	10,968,348	Laser-releasable bonding materials for 3-D IC applications
3	10,961,383	Gradient block copolymers for directed self-assembly
4	10,854,451	Superplanarizing spin-on carbon materials
5	10,770,813	Environmentally sealed, reusable connector for printed flexible electronics
6	10,734,239	High-chi block copolymers with tunable glass transition temperatures for directed self-assembly
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9	10,421,878	High-Chi block copolymers for directed self-assembly
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11	10,352,726	Thin-film resistive-based sensor
12	10,331,032	Photosensitive, developer-soluble bottom anti-reflective coating material
13	10,329,451	All-organic high refractive index materials
14	10,317,291	Environmental sensor system and signal processor
15	10,304,720	Laser ablative dielectric material
16	10,103,048	Dual-layer bonding material process for temporary bonding of microelectronic substrates to carrier substrates
17	RE46,841	Spin-on carbon compositions for lithographic processing
18	9,960,038	Processes to pattern small features for advanced patterning needs
19	9,865,490	Cyclic olefin polymer compositions and polysiloxane release layers for use in temporary wafer bonding processes
20	9,827,757	Methods of transferring device wafers or layers between carrier substrates and other surfaces

21 9,827,740 Polyimides as laser release materials for 3-D IC applications
22 9,738,805 Highly soluble carbon nanotubes with enhanced conductivity
23 9,728,439 High-temperature, spin-on, bonding compositions for temporary wafer bonding using sliding approach
24 9,642,258 All-organic inductor-capacitor tank circuit for radio frequency sensor applications
25 9,640,396 Spin-on spacer materials for double- and triple-patterning lithography
26 9,638,999 Dual-layer light-sensitive developer-soluble bottom anti-reflective coatings for 193-nm lithography
27 D785,058 Spin coater
28 D785,057 Bake plate
29 D783,692 Spin coater/developer
30 9,611,346 Highly crosslinked polymer dielectric films for improved capacitor performance
31 9,580,294 Computer program and method for verifying container of material to be dispensed
32 9,496,164 Cyclic olefin polymer compositions and polysiloxane release layers for use in temporary wafer bonding processes
33 9,482,951 Non-covalently crosslinkable materials for photolithography processes
34 9,472,436 Multiple bonding layers for thin-wafer handling
35 9,349,643 Apparatus and method for thin wafer transfer
36 9,328,246 Nonpolymeric antireflection compositions containing adamantyl groups
37 9,299,778 CVD-free, scalable processes for the production of silicon micro- and nanostructures
38 9,263,314 Multiple bonding layers for thin-wafer handling
39 9,249,013 Silicon hardmask layer for directed self-assembly
40 9,224,631 Multiple bonding layers for thin-wafer handling
41 9,157,003 Highly soluble carbon nanotubes with enhanced conductivity
42 9,127,126 Development of high-viscosity bonding layer through in-situ polymer chain extension
43 9,123,541 Highly etch-resistant polymer block for use in block copolymers for directed self-assembly
44 9,117,757 Silicone polymers with high refractive indices and extended pot life
45 9,111,981 Method for reversibly mounting a device wafer to a carrier substrate
46 9,110,372 Anti-reflective coatings using vinyl ether crosslinkers
47 9,102,129 Spin-on carbon compositions for lithographic processing
48 9,099,512 Article including a device wafer reversibly mountable to a carrier substrate
49 8,968,989 Assist layers for EUV lithography
50 8,940,104 Cleaning composition for temporary wafer bonding materials

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